IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1					Form Type Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier	Information														
Company	name*	Company unique ID			ī	Unique ID Authority					Response Date*				
onsemi												2023-06-08			
Contact N	ame	Title - Contact			]	Phone - Contact*					Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Authorize	d Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date Version Man		Manı	Ianufacturing Site Weight*		Weight*	UOM	Unit Type	
		NCV890104MWR2G 2 MHz Switcher				2023-06-08					50.41	mg	Each		
Manufa	cturing Proccess Informat	ion												,	
	Terminal Plating / Grid Array Ma	Terminal Base Alloy J-STD-020 MS		-STD-020 MSI	L Rating	Peak Process Body Tempe		rature N	ature Max Time at Peak To		ture Nun	nber of Reflow Cyc	eles		
	Matte Tin (Sn) - annealed C		CU Alloy 1			<b>260</b> C		3	0	secon					
Comments															
evel 1 - m	aximum time at peak temperatu	re during sol	dering is 10-3	0 seconds											
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure Level		Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.61	mg	Supplier	Silicon (Si)	7440-21-3		2.61	mg
Die Attach	0.45	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.09	mg
			Supplier	Silver (Ag)	7440-22-4		0.36	mg
Lead Frame	21.41		Supplier	Silver (Ag)	7440-22-4		0.4282	mg
			Supplier	Tin (Sn)	7440-31-5		0.0535	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0471	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0535	mg
			Supplier	Copper (Cu)	7440-50-8		20.8276	mg
Mold Compound-Black	24.75			Epoxy resin	proprietary data		1.1632	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.475	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0248	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		19.9237	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.1632	mg
Plating	1.02	mg	Supplier	Tin (Sn)	7440-31-5		1.02	mg
Wire Bond - Au	0.17	mg	Supplier	Gold (Au)	7440-57-5		0.17	mg